# 技术数据表

）：

L/W/H :3.2*2.7*1.0 mm

Outline Dimensions (L / w / h): 3.2x 2.7 x 1.0mm

* :

Luminous color and colloid: infrared receiver tube /black colloid

ROHS

Environmental protection products Complied With ROHS Directive

Moisture sensitivity level MSL : 3 levels

EIA

EIA standard packaging

*

High energy efficiency, fast startup

## 应用领域（ ）：

# 目录

Catalogue

[redacted]

## 电性参数

| | | | |
|---|---|---|---|
| Power consumption | Pd | 150 | mW |
| Reverse Voltage | VR | 32 | V |
| Operating ambient temperature | Topr | -20°C ~ +85°C | |
| Storage ambient temperature | Tstg | -40°C ~ +85°C | |
| Welding conditions | Tsol | | |

# 典型特性曲线

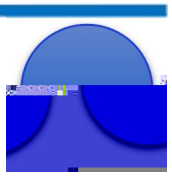
# 外形尺寸

Note

Dimensions are in millimeters

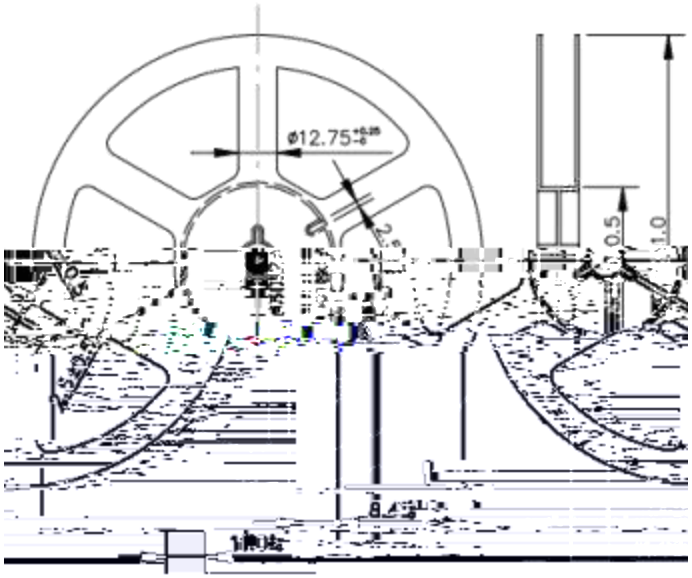
2 ± 0.30mm

Tolerances unless mentioned are ± 0.30mm



# 包装（ ）

## 载带与圆盘尺寸




:

1. (mm)
1. Size unit is mm (mm).
2. ±0.1mm
2. The dimensional tolerance is ± 0.1mm.

## 包装（ ）

Moisture Proof and Antti-Electrostic Foil Bag

Part

## 使用注意事项（1）

300 3 25W

Each terminal is to go to the tip of soldering iron temperature less than 300 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be car ]

XINGLIGHT®

Part No. :XL-

# 使用注意事项（2）

1. 贮存

Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture absorbent minimum.

30 60%RH

Before opening the package, the product should be kept at 30 or less and humidity less than 60% RH, and be used within a year.

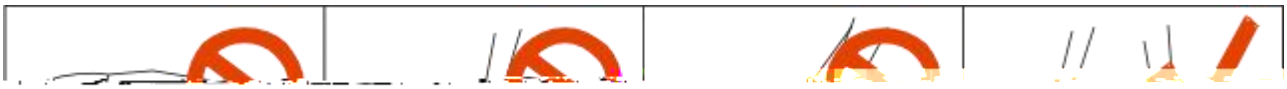
30 40%RH

After opening the package, the product should be stored at 30 or less and humidity less than 40%RH, and be soldered within 168 hours (7day). And it should be welded as soon as possible after the patch. It is recommended that the product be operated at the workshop condition of 30 or less and humidity less than 40%RH.

LED

# 使用注意事项（3）

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.